



CY8C20110-SX2I

CY8C20110-SX2I	
Development Kit	CY3218-CAPEXP1
Automotive Qualified	N
CapSense	Y
Comm. Interface	I2C
Max. Operating Temp. (°C)	85
Max. Operating Voltage (V)	5.50
Min. Operating Temp. (°C)	-40
Min. Operating Voltage (V)	2.40
No. of CapSense IO	10
No. of Dedicated I2C	1
No. of Dedicated SPI	0
No. of GPIOs	10
No. of GPOs	N/A
No. of PWM Channels	0
PWMs	Y
Proximity Sensing	N
Slider Segments	N/A
SmartSense Enabled	N
Tape & Reel	N

PACKAGING/ORDERING

Package	SOIC
No. of Pins	16
Package Dimensions	390 L x 1.5 H x 150 W (Mils)
Package Weight	157.31 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TUBE
Package Carrier Drawing / Orientation	Drawing
Standard Pack Quantity	480
Minimum Order Quantity (MOQ)	480
Order Increment	480
Estimated Lead Time (days)	91
HTS Code	8542.31.0001
ECCN	None
ECCN Suball	EAR99

QUALITY AND ROHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format

IPC 1752 Material Declaration

IPC1752 MATERIAL DECLARATION SOIC 16 (150MILS) (SZ16) - AMKOR - AU WIRE *Last Update: Feb 17, 2019*

IPC1752 MATERIAL DECLARATION SOIC 16 (150MILS) (SZ16) OSE NIPDAU_AU WIRE_CEL9220THF_EN4900G *Last Update: Jan 29, 2019*

RoHS Analysis Certificates (CoA) for Direct Materials

Please click [here](#)

Package Qualification Report

QTP 50701 8/14/16-Lead SOIC Package (150 mil) NiPdAu, MSL3 235C & 260C Reflow OSE-Taiwan (T).pdf *Last Update: Aug 07, 2015*

Device Qualification Reports

FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report.

QTP 073803 PSOC (8C20100) IN S4AD-5 TECHNOLOGY AT FAB-4 CMI *Last Update: Sep 20, 2016*

QTP 090403: NANO PSOC 8C20100A (CAPSENSE VENUS) PRODUCT FAMILY S4AD-5 TECHNOLOGY, FAB5 QUALIFICATION REPORT *Last Update: Sep 17, 2016*